



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



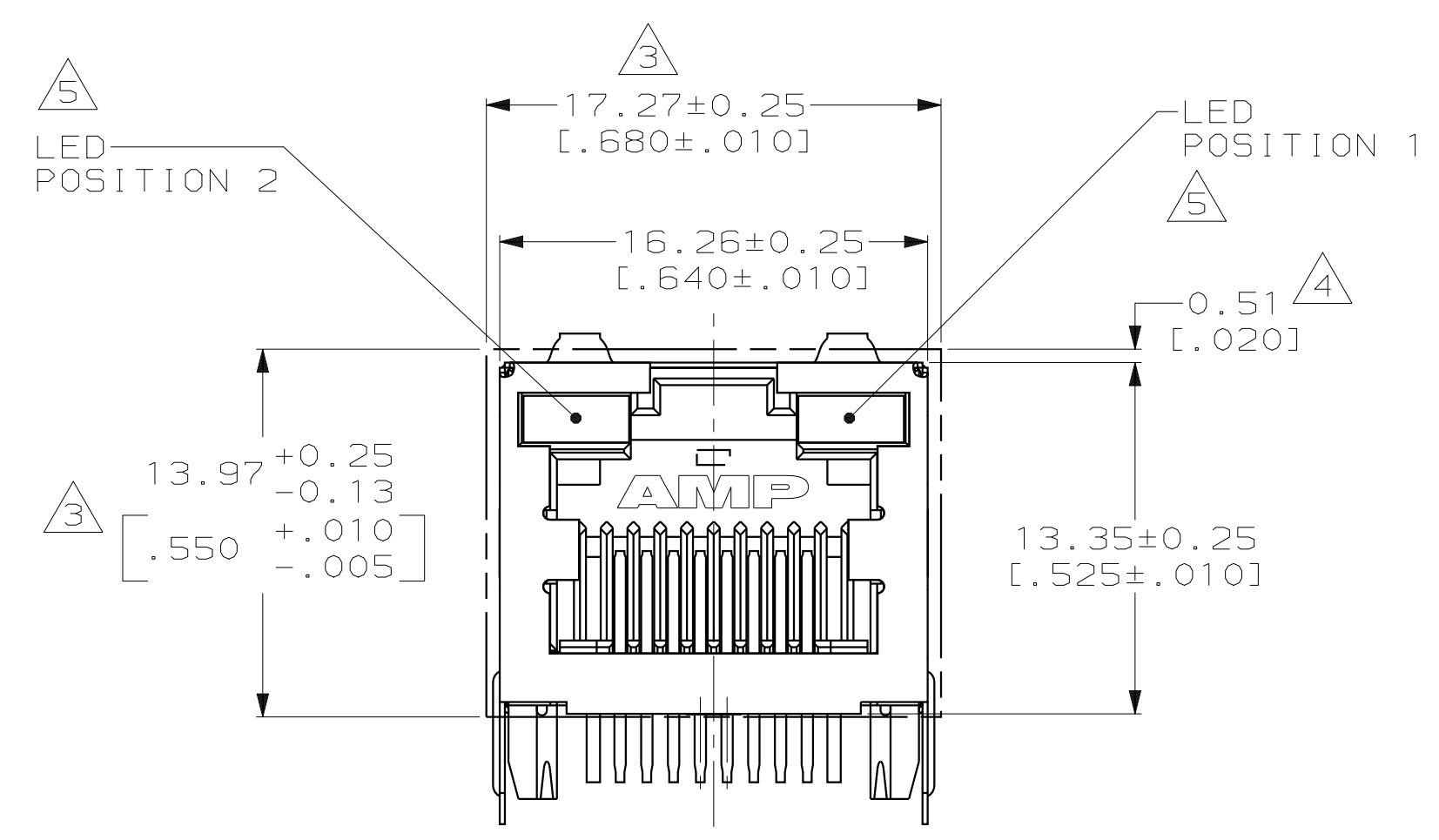
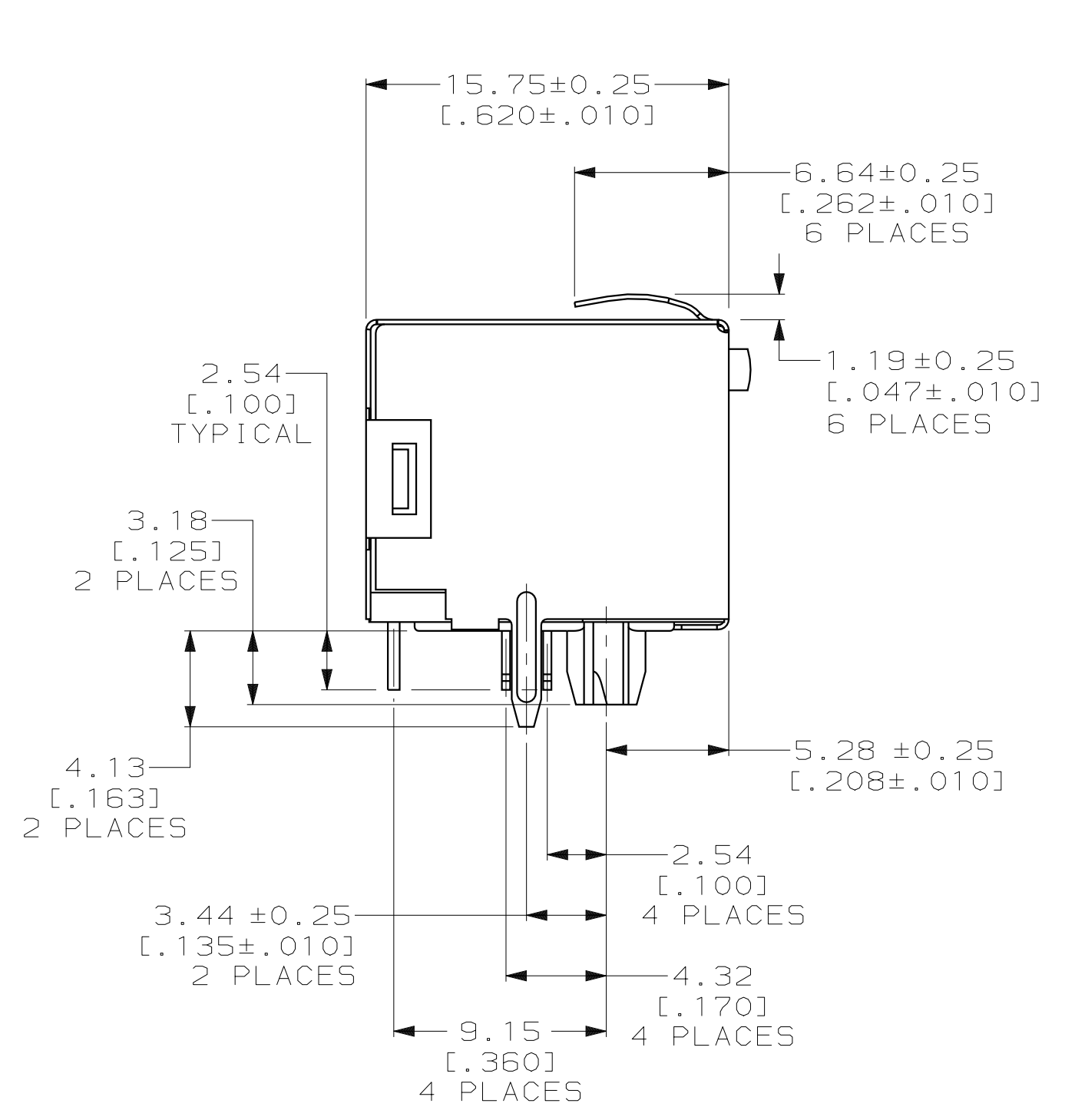
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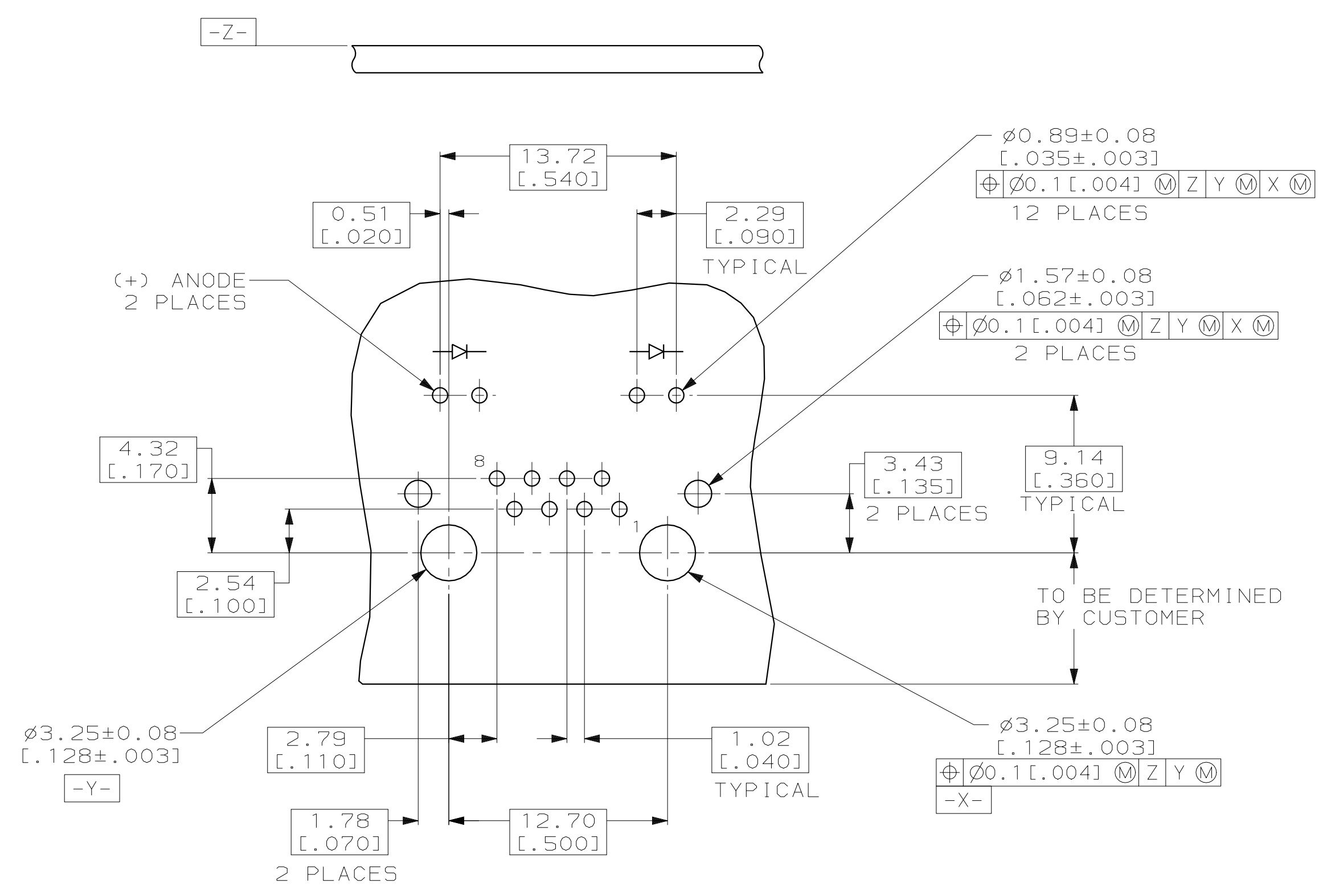
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





△ MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, HEAT DEFLECTION TEMPERATURE RATING 278°C [532°F] AT 1.8MPa [264 PSI], BLACK, UL94V-0. TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK TIN IN SOLDER AREA, 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM SnAgCu POST DIPPED ON PCB GROUND TABS. LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 2.29µm[.000090] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE. POST-PLATED WITH 6.35µm [.000250] MINIMUM TIN. LEDS NOT DESIGNED FOR IR REFLOW SOLDERING.

- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- 6. TRAY PACKAGED.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

INDICATOR COLOR	PART NUMBER
GREEN	6116615-5
GREEN	6116615-4
POSITION 2	POSITION 1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B KUHNLY 140CT2004	AMP Incorporated Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]		CHK B KUHNLY 140CT2004	NAME INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, TOP PANEL GROUNDS, LEDS, TIN PLATED SOLDER TAILS
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S FLICKINGER 140CT2004	PRODUCT SPEC 108-1163-4
0 PLC ±.005		PRODUCT SPEC	APPLICATION SPEC
1 PLC ±.01		SIZE A1	SCALE 4:1
2 PLC ±.02		WEIGHT	SHEET 1 OF 1
3 PLC ±.03		CUSTOMER DRAWING	REV 0
4 PLC ±.05			
ANGLES ±.005			
FINISH			